

## SSC8029GQ4

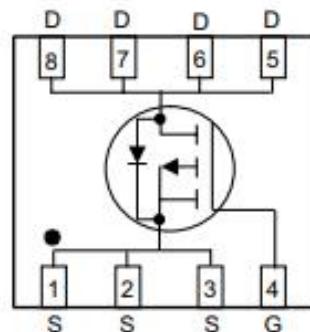
### P-Channel Enhancement Mode MOSFET

#### ➤ Features

VDS	VGS	RDS(on) Typ.	ID
-20V	±12V	17mΩ@-4V5	-15A
		21mΩ@-2V5	
		26mΩ@-1V8	

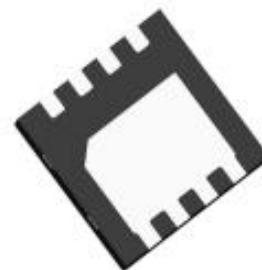
#### ➤ Pin configuration

Top view



#### ➤ Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device is particularly suited for low voltage power management requiring a wide range of given voltage ratings(4.5V~18V) such as load switch and battery protection.



Bottom View

#### ➤ Applications

- Load Switch
- NB battery
- DCDC conversion

8029  
YW

#### ➤ Ordering Information

Device	Package	Shipping
SSC8029GQ4	DFN3x3	5000/Reel

(Y: year/W: week)

Marking

➤ **Absolute Maximum Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-20	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current <sup>a</sup>	-15	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-45	A
$P_D$	Power Dissipation <sup>c</sup>	15	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	2.5	W
$T_J$	Operation junction temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^\circ\text{C}$

➤ **Thermal Resistance Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>		60	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		9	

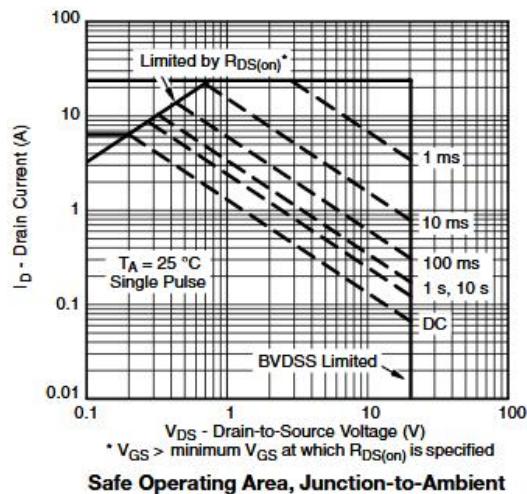
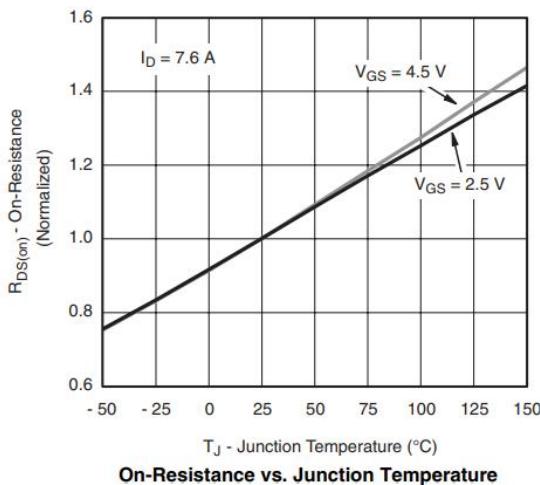
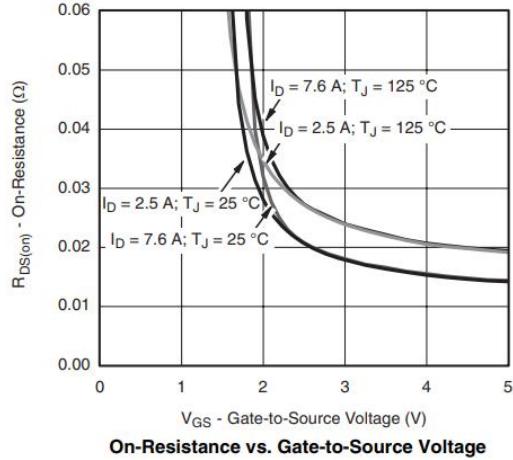
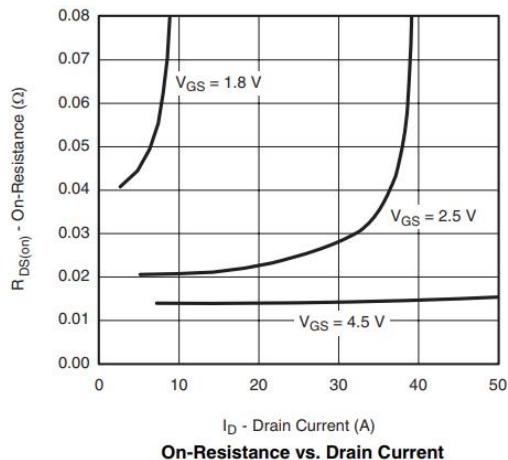
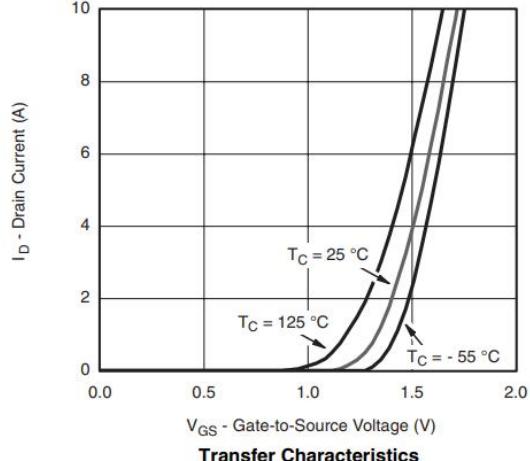
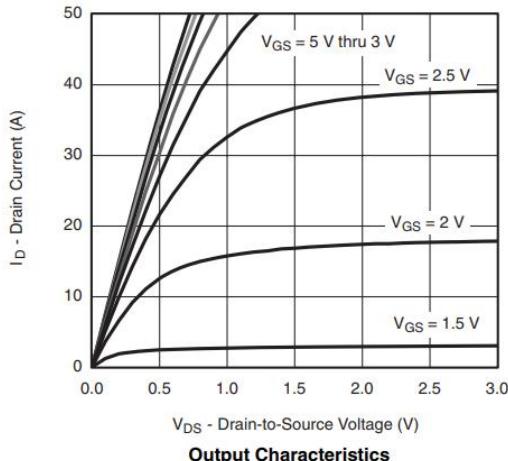
Note:

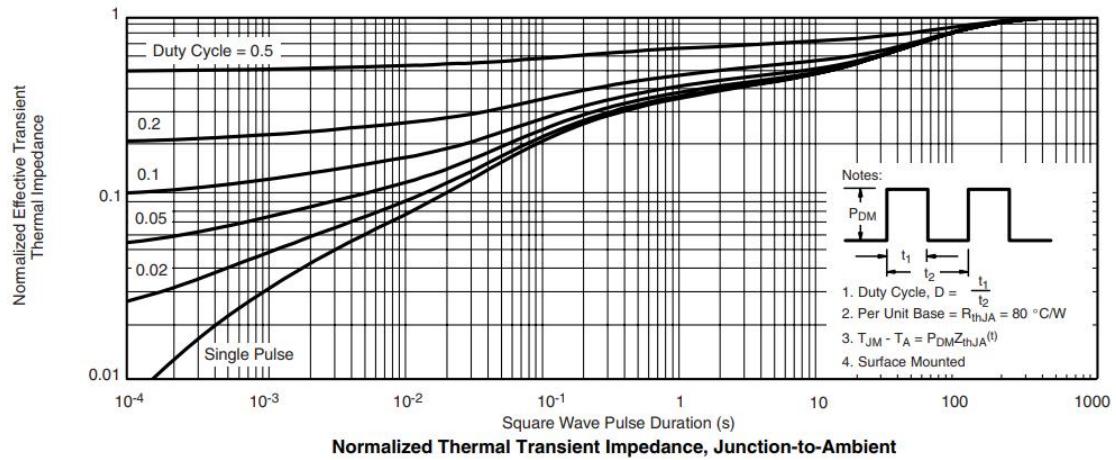
- a. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with  $T_A=25^\circ\text{C}$ .The value in any given application depends on the user specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

➤ **Electronics Characteristics( $T_A=25^\circ C$  unless otherwise noted)**

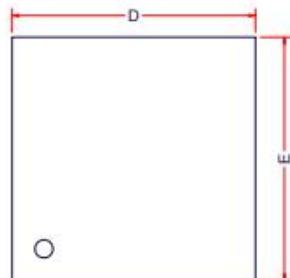
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min</b>	<b>Typ.</b>	<b>Max</b>	<b>Unit</b>
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, ID=-250\mu A$	-20			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=-250\mu A$	-0.5	-0.6	-1	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=-4.5V, ID=-5.5A$		17	22	$m\Omega$
		$V_{GS}=-2.5V, ID=-2.5A$		21	27	
		$V_{GS}=-1.8V, ID=-1.8A$		26	50	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 12V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=-5V, ID=-10A$		25		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, IS=-1A$		-0.75	-1.3	V
$C_{iss}$	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$		1828		$pF$
$C_{oss}$	Output Capacitance			203		
$C_{rss}$	Reverse Transfer Capacitance			201		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=-4.5V, V_{DS}=-10V, RL=6\Omega, RG=6\Omega, ID=-6.5A$		16		$ns$
$Tr$	Rise time			14		
$T_{D(OFF)}$	Turn-off delay time			78		
$T_f$	Fall time			66		

➤ **Typical Characteristics**( $T_A=25^\circ\text{C}$  unless otherwise noted)

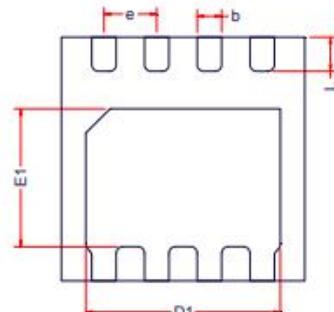




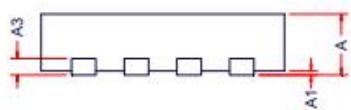
➤ Package Information



TOP VIEW



BOTTOM VIEW

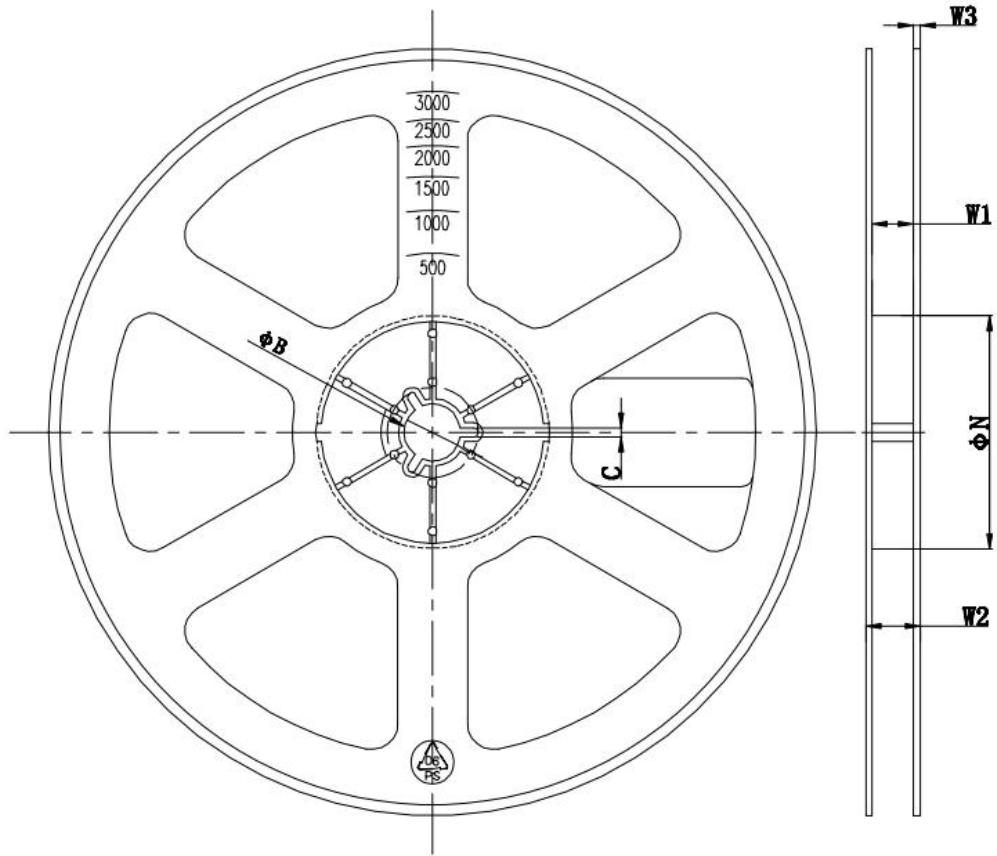


SIDE VIEW

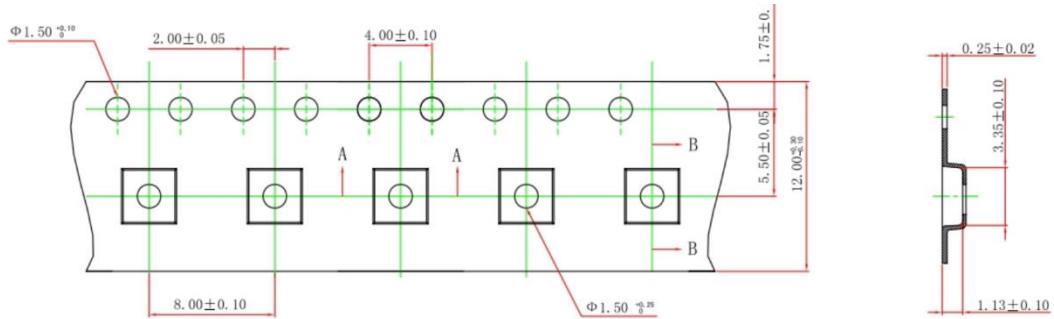
DFN3x3-8L

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.20Ref		
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D1	2.35	2.40	2.45
E1	1.65	1.70	1.75
b	0.25	0.30	0.35
e	0.65BSC		
L	0.37	0.42	0.47

➤ Tape and Reel



$\Phi A$	$\Phi N$	$\Phi B$	C	W1	W2	W3
$178 \pm 2$	$54 \pm 2$	$13.2 \pm 0.3$	$2.2 \pm 0.3$	$9.5 \pm 1$	$13_{\max}$	$1.4 \pm 0.4$



SECTION B-B



➤ **History Version**

V1.0		
V2.0		
V2.1	Delete Rdson-1.5V.	2022-09-14

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